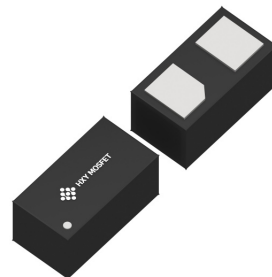




Discription

The HDESD3V3X1BCSF-7 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN0603-2L

Features

- ★ Transient protection for high-speed data lines
IEC 61000-4-2(ESD) $\pm 15\text{kV}$ (Contact)
 $\pm 8\text{kV}$ (Air)
IEC 61000-4-4(EFT) 40A (5/50 ns)
- ★ Package optimized for high-speed lines
- ★ Low capacitance: 0.55pF (Typical)
- ★ Ultra-small package (0.6mmx0.3mmx0.3mm)
- ★ Protects one I/O line
- ★ Low clamping voltage
- ★ Low leakage current



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
HDESD3V3X1BCSF-7	DFN0603-2L	15000

Absolute Ratings($T_{amb} = 25^{\circ}\text{C}$)

Symbol	Parameter	Value	Units
P_{PP}	Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	96	W
T_L	Maximum lead temperature for soldering during 10s	260	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
T_{op}	Operating Temperature Range	-40 to +125	$^{\circ}\text{C}$
T_j	Maximum junction temperature	150	$^{\circ}\text{C}$
	IEC61000-4-2 (ESD)	air discharge contact discharge	± 8 ± 15 KV

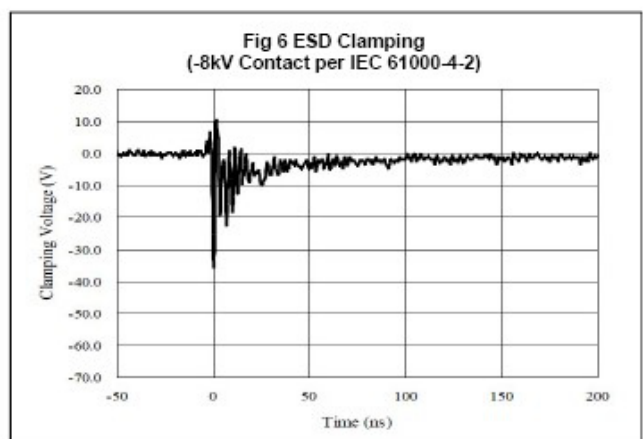
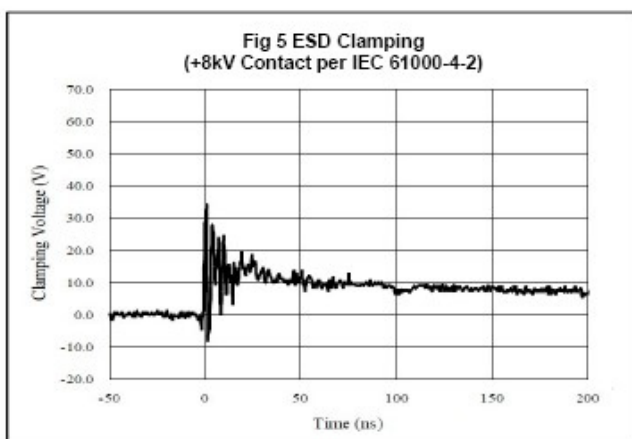
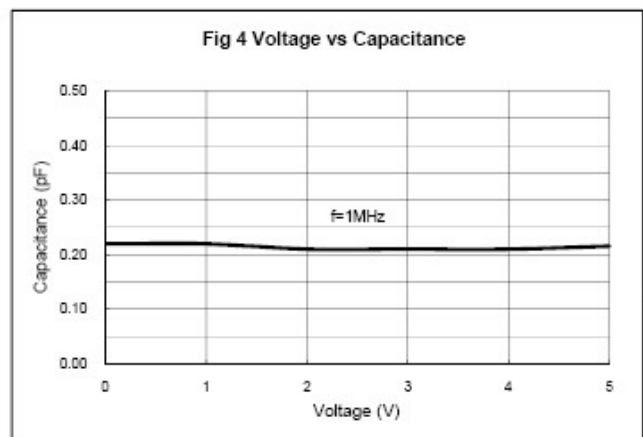
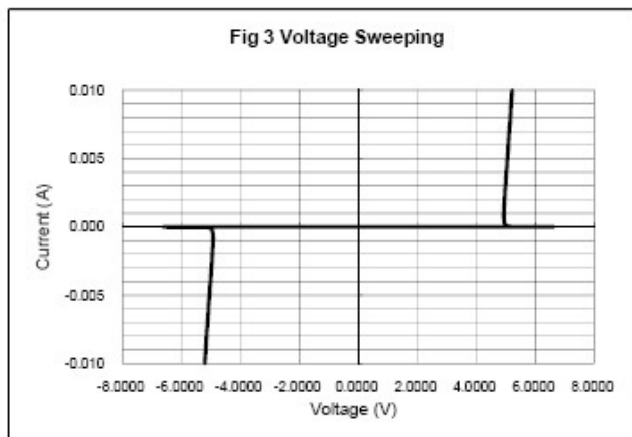
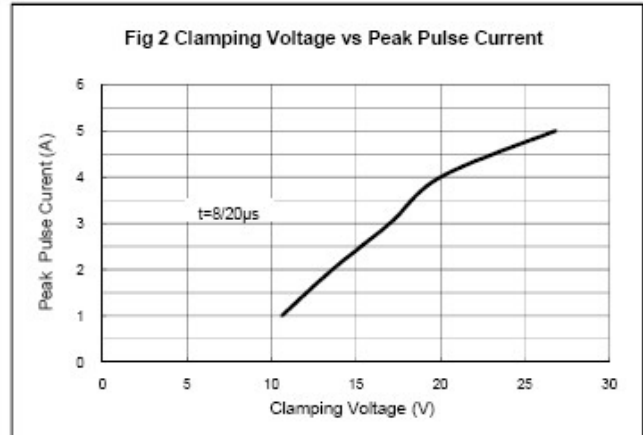
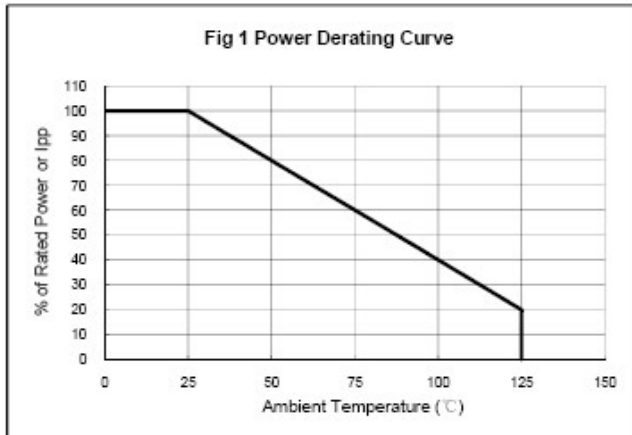


Electrical Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				3.3	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1mA$	4.2			V
I_R	Reverse Leakage Current	$V_{RWM} = 3.3V$			100	nA
V_C	Clamping Voltage	$I_{PP} = 1A, t_p = 8/20\mu s$			12	V
		$I_{PP} = 4A, t_p = 8/20\mu s$			24	V
C_J	Junction Capacitance	$V_R = 0V, f = 1MHz$		0.55	0.7	pF

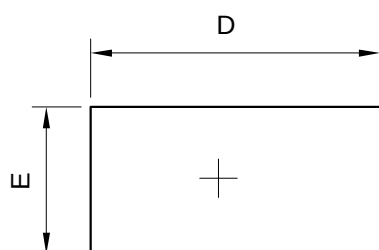


Typical Characteristics

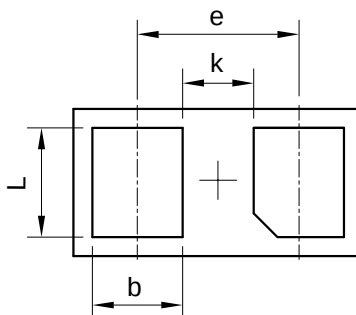




Outline And Dimensions



TOP VIEW



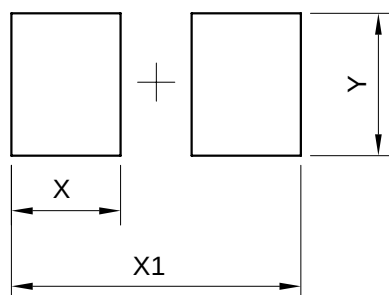
BOTTOM VIEW

DFN0603-2L			
Dim	Min	Typ.	Max
D	0.58	0.61	0.64
E	0.28	0.31	0.34
e	-	0.34	-
L	0.20	0.23	0.26
b	0.16	0.19	0.22
A	0.25	0.28	0.31
k	0.12	0.15	0.18
All Dimensions in mm			



SSIDE VIEW

Soldering Footprint



DFN0603-2L	
DIM	(mm)
X	0.23
X1	0.61
Y	0.30



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